

NCE40P05S

NCE P-Channel Enhancement Mode Power MOSFET

Description

The NCE40P05S uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

V_{DS} =-40V,I_D =-5.3A

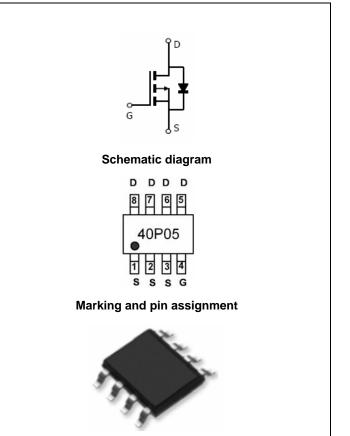
 $R_{DS(ON)}$ <80m Ω @ V_{GS} =-10V

 $R_{DS(ON)}$ <120m Ω @ V_{GS} =-4.5V

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation

Application

- Power switching application
- Hard switched and high frequency circuits
- DC-DC converter



SOP-8 top view

Package Marking and Ordering Information

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Device Marking	Device Marking Device		Reel Size	Tape width	Quantity		
40P05	NCE40P05S	SOP-8	Ø330mm	12mm	2500 units		

Absolute Maximum Ratings (T_A=25 ℃unless otherwise noted)

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Parameter	Symbol	Limit	Unit			
Drain-Source Voltage	V _{DS}	-40	V			
Gate-Source Voltage	V _{GS}	±20	V			
Drain Current-Continuous	I _D	-5.3	А			
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	-3.65	Α			
Pulsed Drain Current	I _{DM}	-20	Α			
Maximum Power Dissipation	P _D	2.0	W			
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	$^{\circ}\!\mathbb{C}$			

Thermal Characteristic

Thermal Resistance ,Junction-to-Ambient ^(Note 2)	$R_{ heta JA}$	62.5	°C/W

Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit



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Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-40	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-40V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	·					
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=-250\mu A$	-1.0	-1.9	-2.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-10V, I _D =-5A	-	67	80	mΩ
Drain-Source On-State Resistance	TOS(ON)	V_{GS} =-4.5 V , I_D =-4 A	-	92	120	mΩ
Forward Transconductance	g FS	V _{DS} =-15V,I _D =-3.1A	10	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss}	\/ 00\/\/ 0\/	-	600	-	PF
Output Capacitance	C _{oss}	V_{DS} =-20V, V_{GS} =0V, F=1.0MHz	-	90	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.UIVIHZ	-	70	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	9	-	nS
Turn-on Rise Time	t _r	V_{DD} =-20 V , R_L =2 Ω	-	8	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =-10 V , R_{GEN} =3 Ω	-	28	-	nS
Turn-Off Fall Time	t _f		-	10	-	nS
Total Gate Charge	Qg	\/ 00\/ L 5A	-	14	-	nC
Gate-Source Charge	Q _{gs}	V_{DS} =-20V, I_{D} =-5A,	-	2.9	-	nC
Gate-Drain Charge	Q_{gd}	V _{GS} =-10V	-	3.8	-	nC
Drain-Source Diode Characteristics	<u> </u>		•			
Diode Forward Voltage (Note 3)	V _{SD}	V_{GS} =0 V , I_{S} =-5 A	-	-	1.2	V
Diode Forward Current (Note 2)	Is		-	-	-5.3	Α

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- **3.** Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production



Typical Electrical and Thermal Characteristics

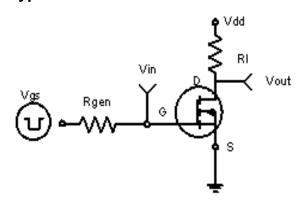


Figure 1:Switching Test Circuit

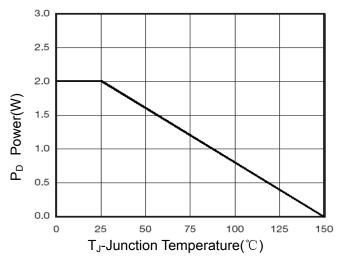


Figure 3 Power Dissipation

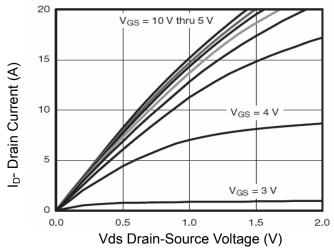


Figure 5 Output Characteristics

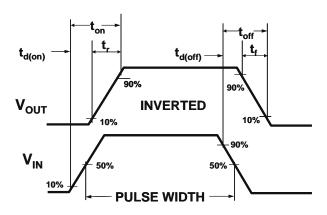


Figure 2:Switching Waveforms

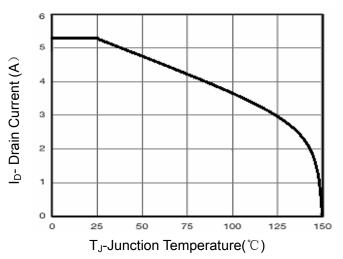


Figure 4 Drain Current

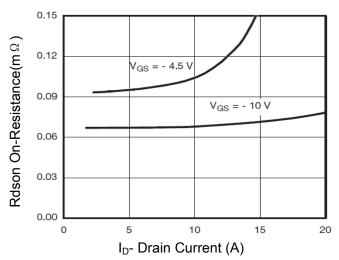


Figure 6 Drain-Source On-Resistance



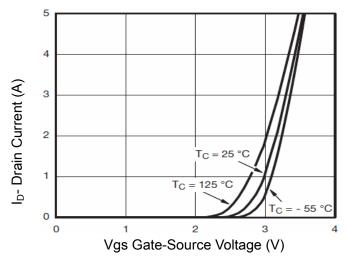


Figure 7 Transfer Characteristics

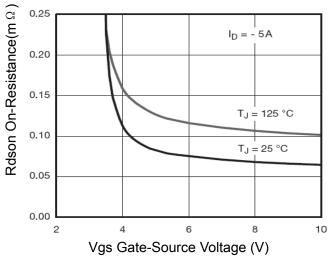
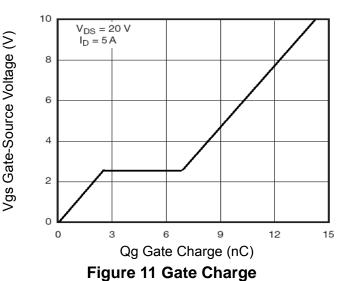


Figure 9 Rdson vs Vgs



1.8 V_{GS} = - 10 V; I_D = - 5A V_{GS} = - 10 V; I_D = - 5A 1.2 0.6 - 50 - 25 0 25 50 75 100 125 150 T_J-Junction Temperature(°C)

Figure 8 Drain-Source On-Resistance

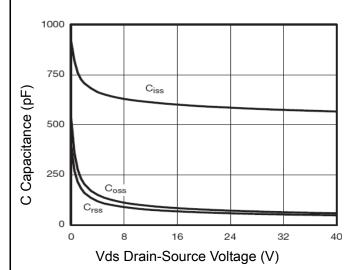


Figure 10 Capacitance vs Vds

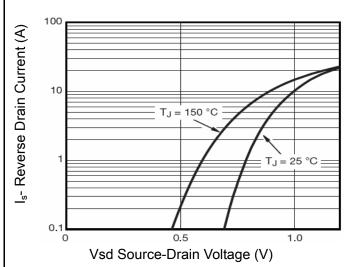


Figure 12 Source- Drain Diode Forward



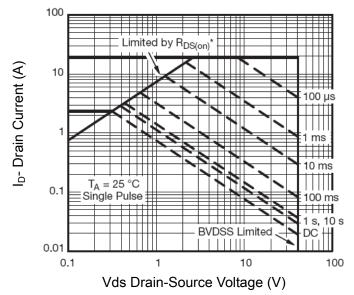


Figure 13 Safe Operation Area

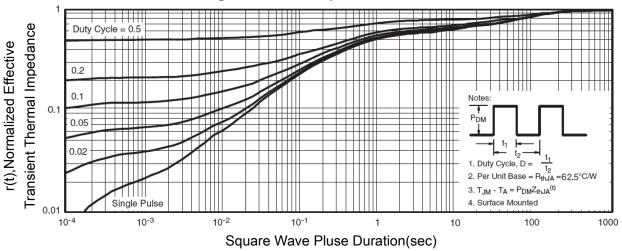
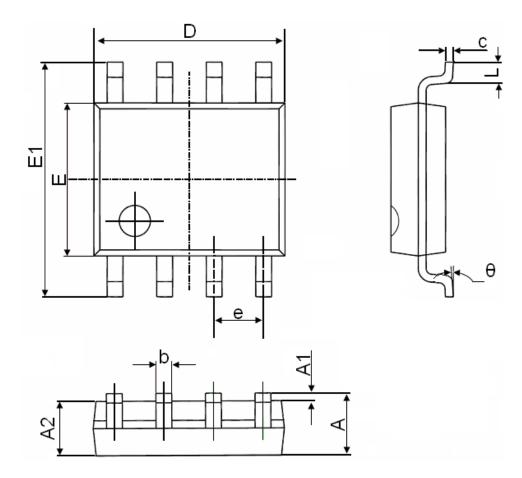


Figure 14 Normalized Maximum Transient Thermal Impedance

Pb Free Product



SOP-8 Package Information



Symbol	Dimensions I	n Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
С	0.170	0.250	0.006	0.010	
D	4.700	5.100	0.185	0.200	
E	3.800	4.000	0.150	0.157	
E1	5.800	6.200	0.228	0.244	
е	1.270	1.270(BSC)		(BSC)	
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	



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